



TGA2731-SM

2.7–4.0 GHz Driver Amplifier

General Description

Qorvo's TGA2731-SM is a driver amplifier fabricated on Qorvo's QPHT25 0.25 μm GaAs production process. The TGA2731-SM operates from 2.7 to 4.0 GHz and provides > 30.7 dBm of output power with > 22.7 dB of large signal gain. The TGA2731-SM also includes a 13 dB attenuator at the input, and a simple resistively coupled power detector at the output. The amplifier can be operated from a single supply in the self-biased mode.

The TGA2731-SM is offered in a 5x5 mm plastic QFN. It is well-matched to 50 ohms, and includes integrated DC blocking caps on both RF ports allowing for simple system integration.

Lead-Free & RoHS compliant.

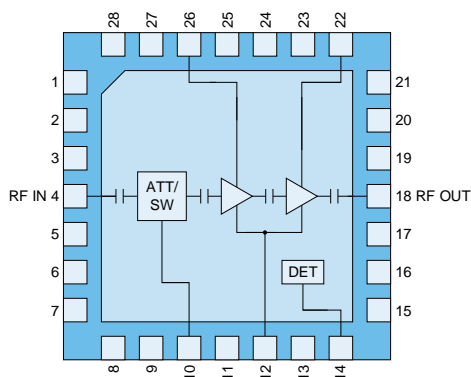
Evaluation Boards are available on request.



Product Features

- Frequency Range: 2.7-4.0 GHz
- Small Signal Gain: > 24 dB
- Power: > 30.7 dBm
- PAE: $> 22\%$
- IM3: < -32 dBc (@ 3.5 GHz)
- Input Return Loss > 7 dB
- Output Return Loss > 11 dB
- Self-Bias: $V_D = 6$ V, $V_G = 0$ V, $I_{DQ} = 900$ mA
- Single Supply Operation
- Package Dimensions: 5.0 x 5.0 x 0.85 mm

Functional Block Diagram



Applications

- Commercial and Military Radar
- Communications
- Test Instrumentation

Ordering Information

| Part | Description |
|----------------|------------------------------|
| TGA2731-SM | 2.7–4.0 GHz Driver Amplifier |
| TGA2731-SM EVB | Evaluation Board |

Absolute Maximum Ratings

| Parameter | Value/Range |
|---|----------------------|
| Drain Voltage (V_D) | 9 |
| Gate Voltage Limits (V_G) | -1 V/0V |
| Drain Current (I_D) | 1000 mA |
| Gate Current ($+I_G$ @ $T_{CH} = 150\text{ }^\circ\text{C}$) | -5.28/24.8 mA |
| Power Dissipation, $T_{BASE} = 85\text{ }^\circ\text{C}$, $T_{CH} = 200\text{ }^\circ\text{C}$, CW operation (P_{DISS}) | 4.50 W |
| Input Power, CW, 50 Ω^1 | 13 dBm |
| Input Power, CW, VSWR 10:1 ¹ | 13 dBm |
| Channel Temperature (T_{CH}) | 200 $^\circ\text{C}$ |

Notes:

1. $V_D = 6\text{ V}$, $V_G = 0\text{ V}$, $T_{BASE} = 85\text{ }^\circ\text{C}$

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied.

Recommended Operating Conditions

| Parameter | Value/Range |
|--|-------------|
| Drain Voltage (V_D) | 6 V |
| Gate Voltage (V_G) (self-biased mode) | 0 V |
| Quiescent Drain Current (I_{DQ}) | 900 mA |
| Operating Drain Current (I_{D_DRIVE}) | 800-975 mA |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

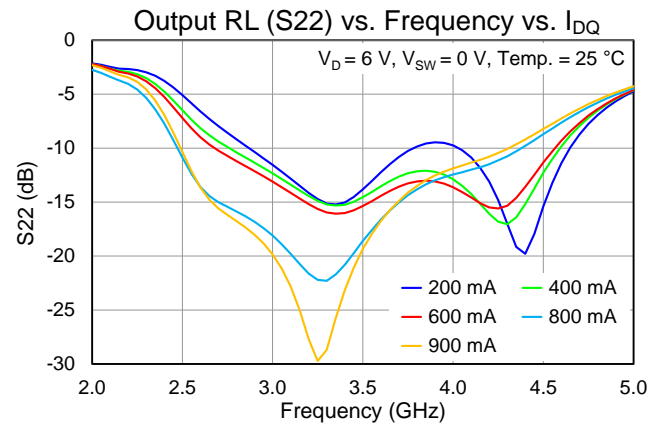
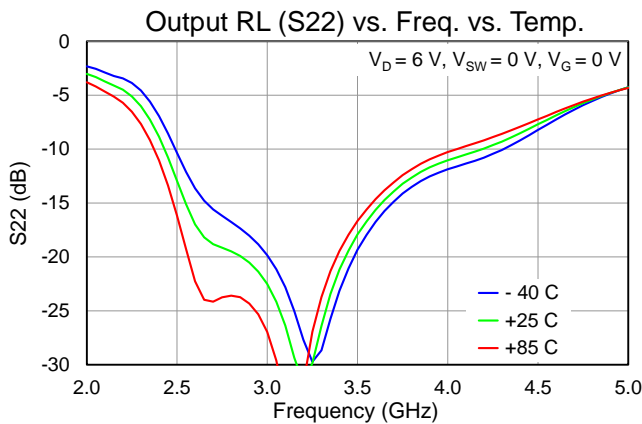
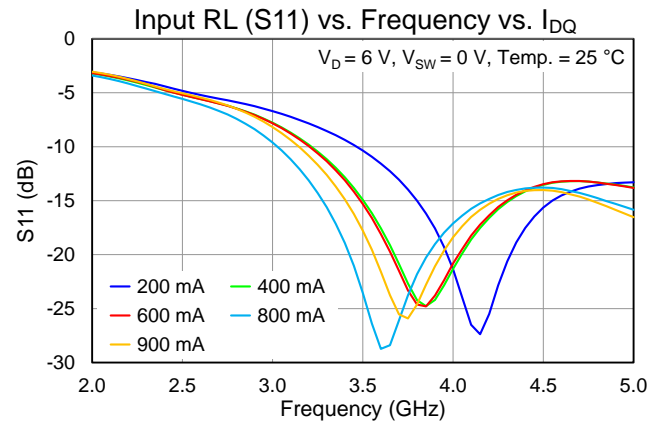
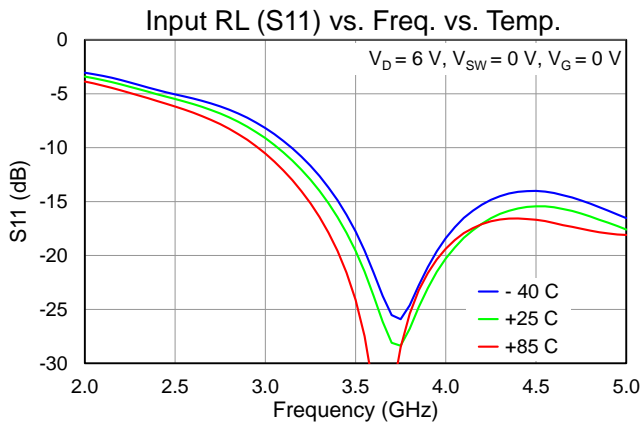
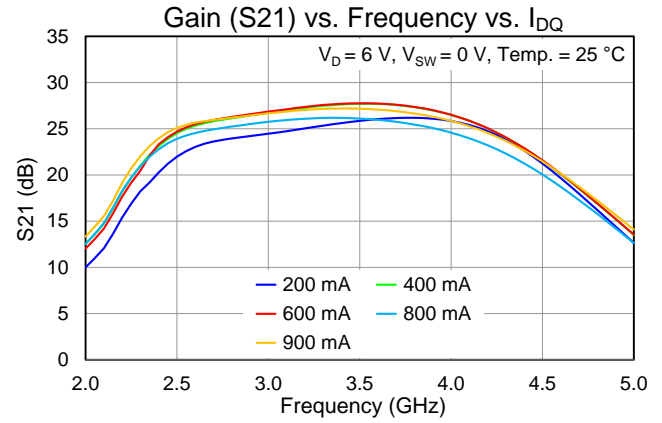
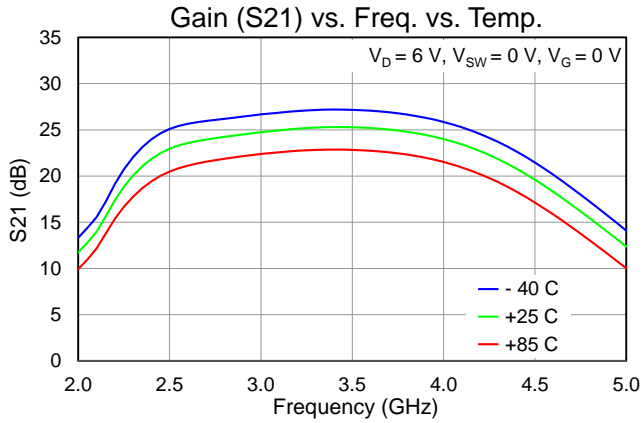
Electrical Specifications

Test conditions, unless otherwise noted: $T = 25\text{ }^\circ\text{C}$, $V_D = 6\text{ V}$, $V_G = 0\text{ V}$, $I_{DQ} \sim 900\text{ mA}$, $V_{SW} = 0\text{ V}$, part mounted to EVB
Output Power and PAE pulse conditions: $PW = 100\text{ }\mu\text{s}$, $DC = 20\%$

| Parameter | Min | Typical | Max | Units |
|---|-----|---------|-----|----------------------|
| Operating Frequency Range | 2.7 | | 4.0 | GHz |
| Output Power (Pulsed, $P_{in} = 8\text{ dBm}$) | | > 30.7 | | dBm |
| Power Added Efficiency (Pulsed, $P_{in} = 8\text{ dBm}$) | | > 22 | | % |
| Small Signal Gain | | > 24 | | dB |
| Input Return Loss | | > 7 | | dB |
| Output Return Loss | | > 11 | | dB |
| IM3 ($P_{OUT}/\text{tone} \leq 23\text{ dBm}$, 3.5 GHz) | | < -32 | | dBc |
| 2 nd Harm. Suppression ($P_{OUT} \leq 30\text{ dBm}$, 3.5 GHz) | | < -39 | | dBc |
| 3 rd Harm. Suppression ($P_{OUT} \leq 30\text{ dBm}$, 3.5 GHz) | | < -44 | | dBc |
| Output Power Temperature Coefficient | | -0.004 | | dB/ $^\circ\text{C}$ |

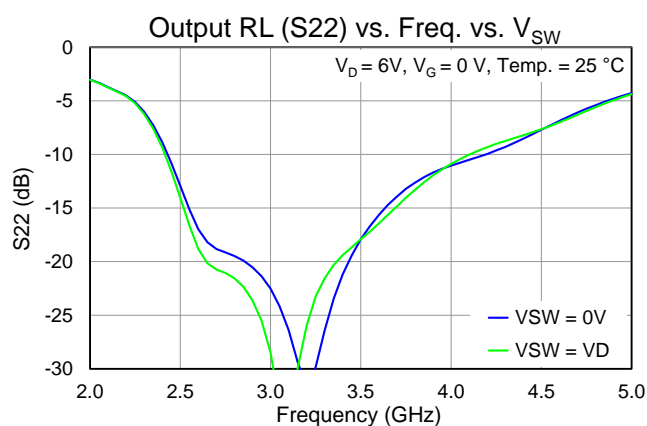
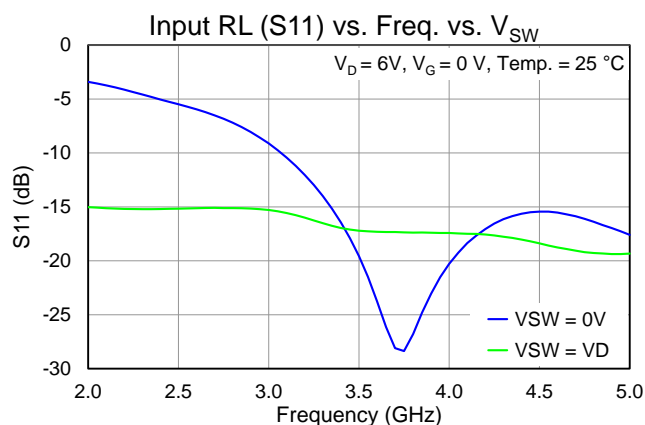
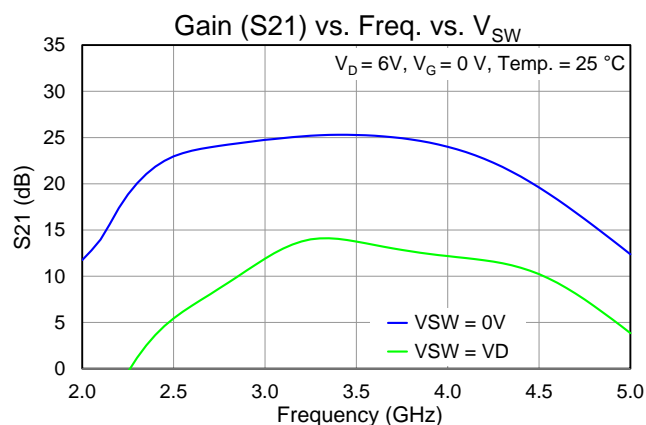
Typical Performance (Small Signal)

Test conditions, unless otherwise noted: T = 25 °C, part mounted to EVB



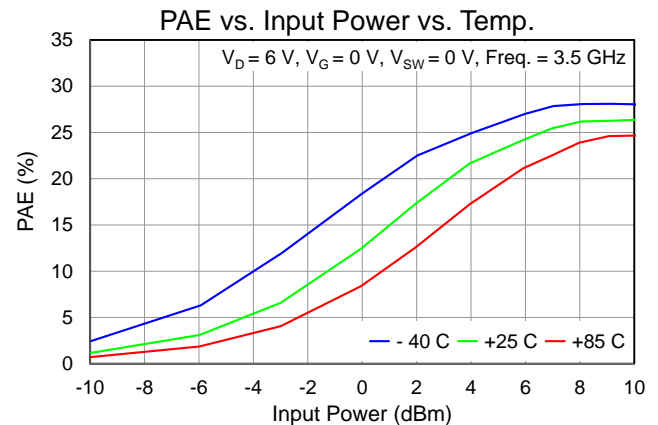
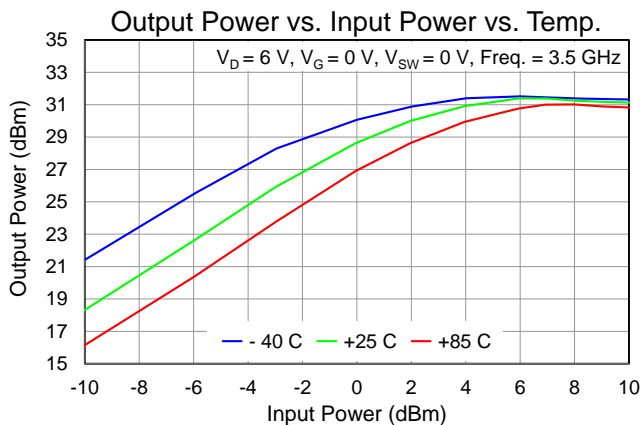
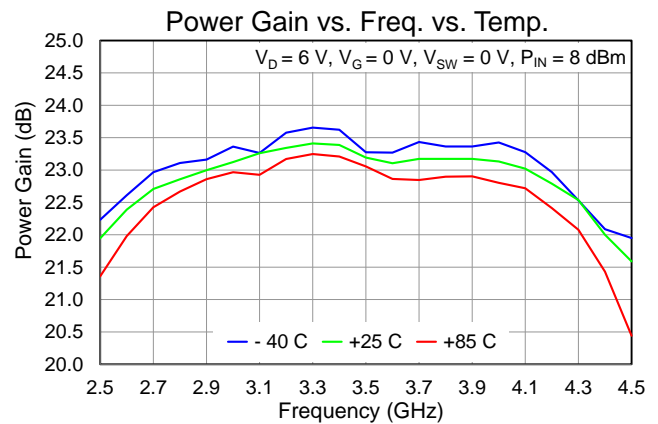
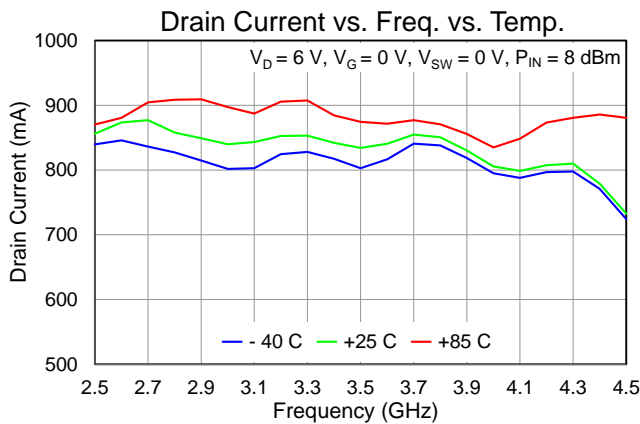
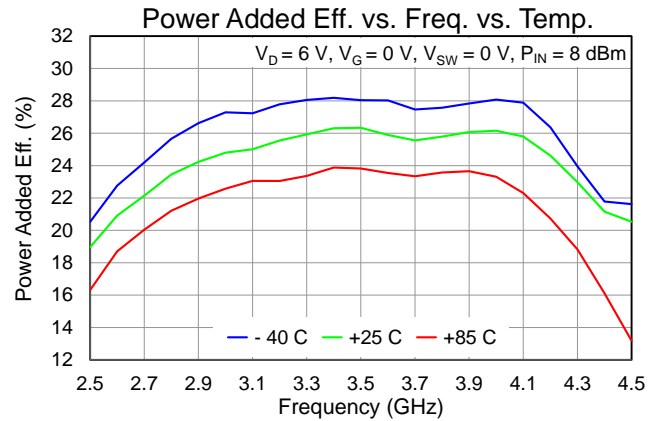
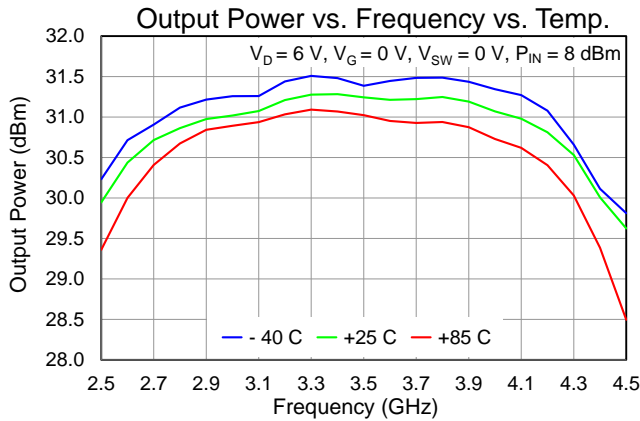
Typical Performance – (Small Signal)

Test conditions, unless otherwise noted: T = 25 °C, part mounted to EVB



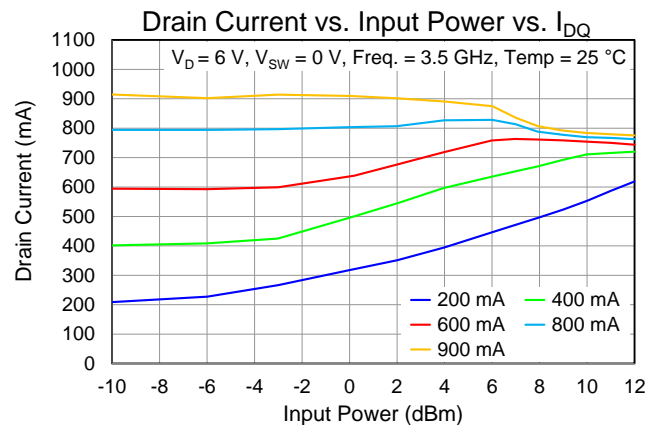
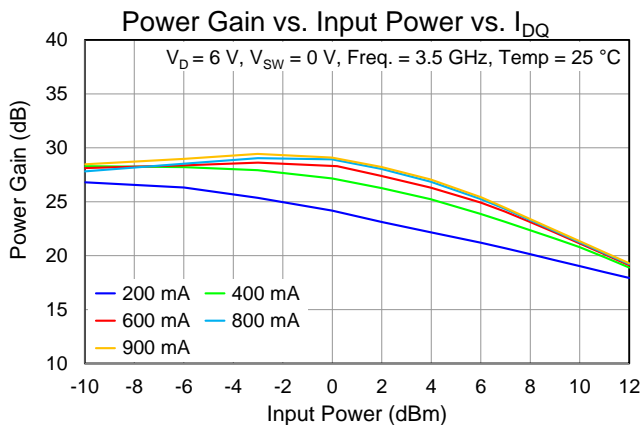
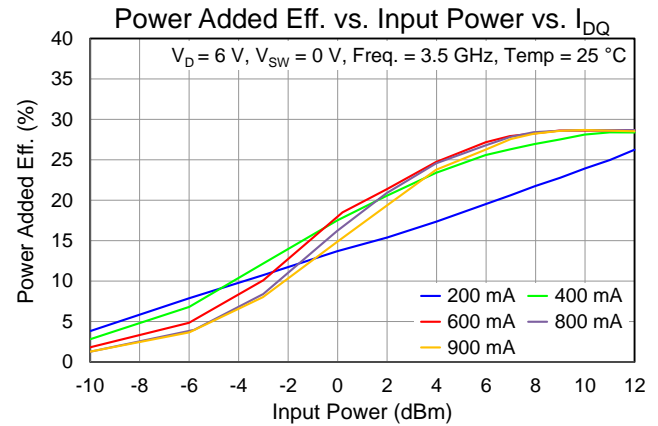
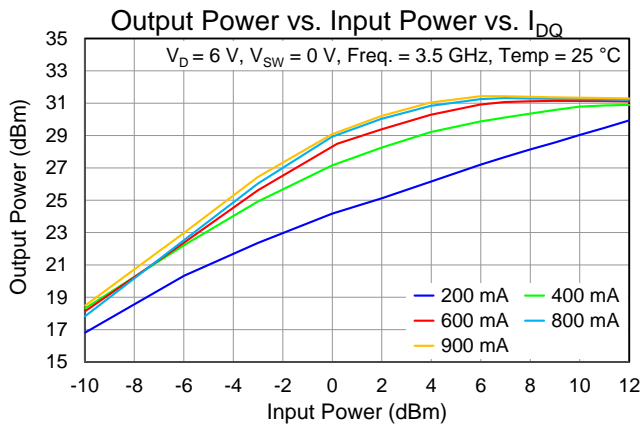
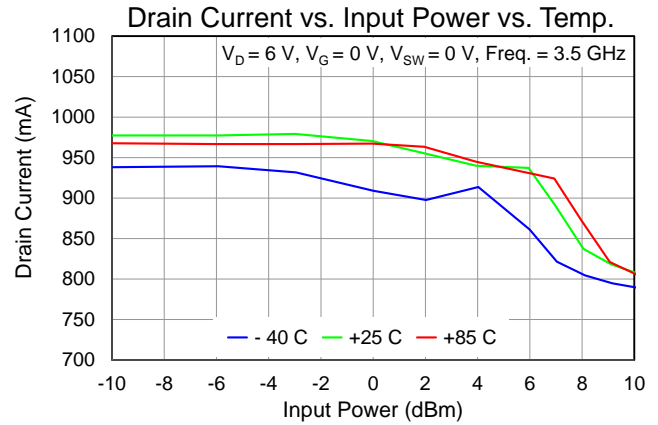
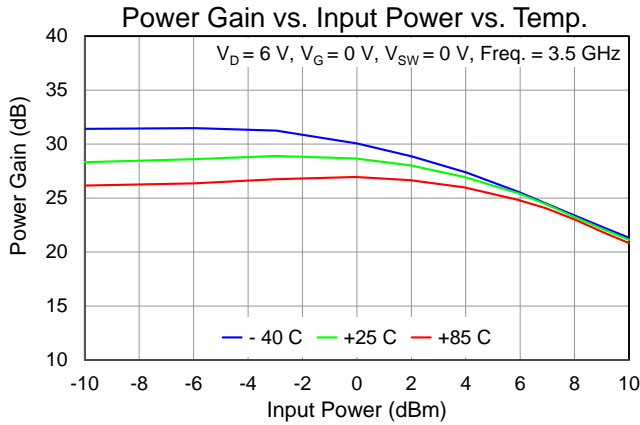
Typical Performance – Large Signal (Pulsed)

Test conditions, unless otherwise noted: T = 25 °C, part mounted to EVB, Pulse Power: PW = 100 us, DC = 20%



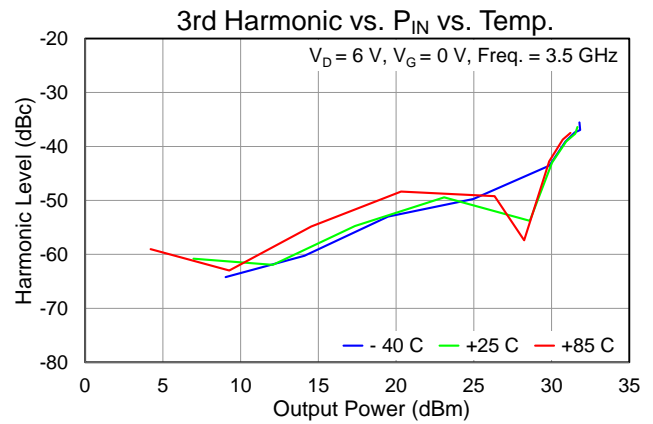
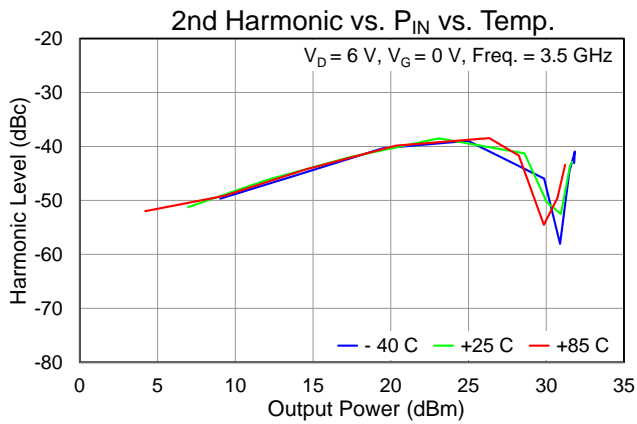
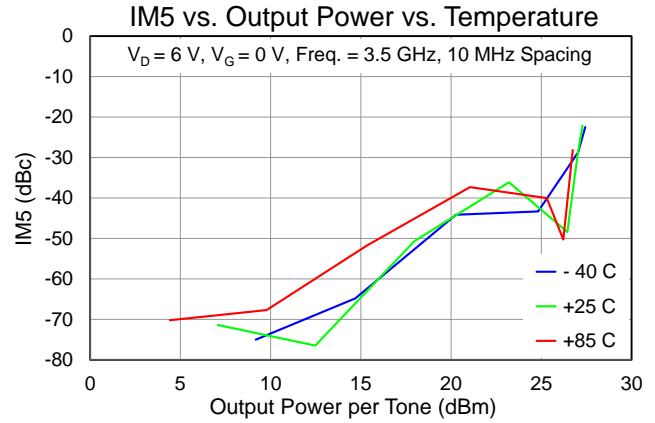
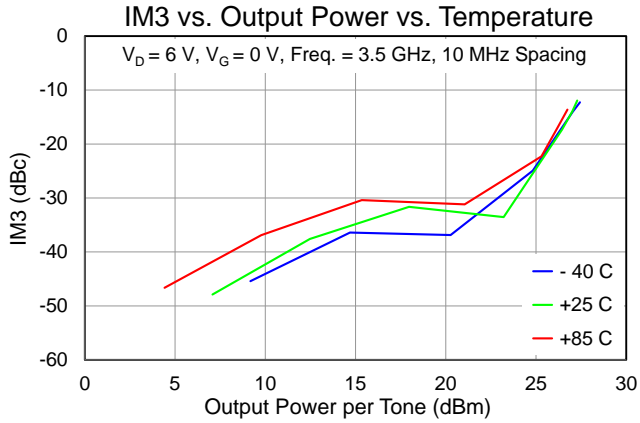
Typical Performance – Large Signal (Pulsed)

Test conditions, unless otherwise noted: T = 25 °C, part mounted to EVB, Pulse Power: PW = 100 us, DC = 20%



Typical Performance - Linearity

Test conditions, unless otherwise noted: $T = 25^\circ\text{C}$, $V_{\text{SW}} = 0\text{ V}$, part mounted to EVB



Thermal and Reliability Information

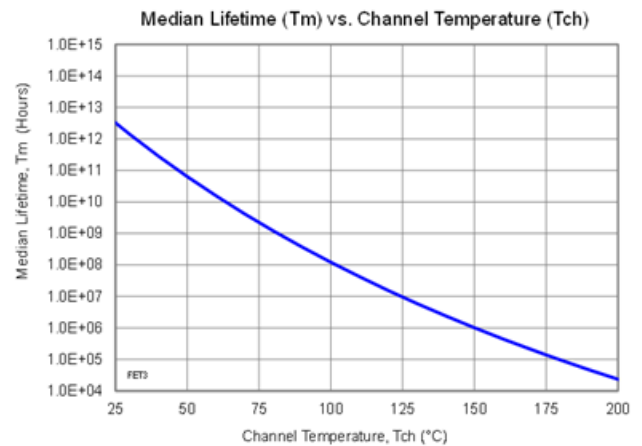
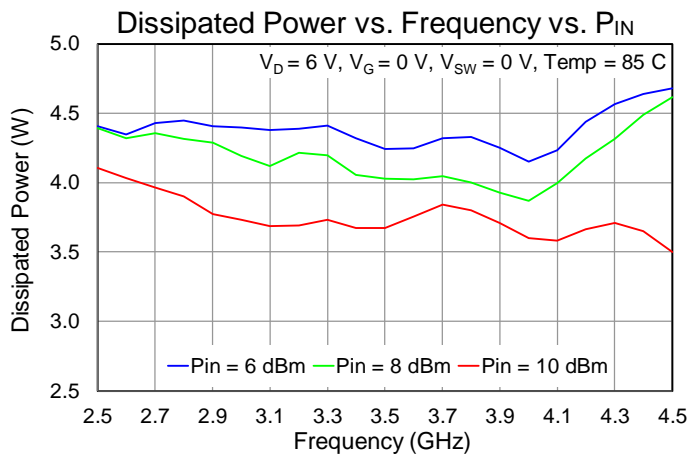
| Parameter | Conditions | Value | Units |
|---|--|-------|-------|
| Thermal Resistance (θ_{JC}) ⁽¹⁾ | T _{BASE} = 85 °C, V _D = 6 V, V _G = 0 V, I _{D_DRIVE} = 900 mA, Pulse Power Conditions: Pulse Width = 100 us, Duty Cycle = 10%, P _{IN} = 6 dBm, P _{OUT} = 30.8 dBm, P _{DISS(PULSE)} = 4.45 W | 10.4 | °C/W |
| Channel Temperature (T _{CH}) ⁽¹⁾ | | 131.2 | °C |

Notes:

1. Package backside temperature fixed at 85 °C

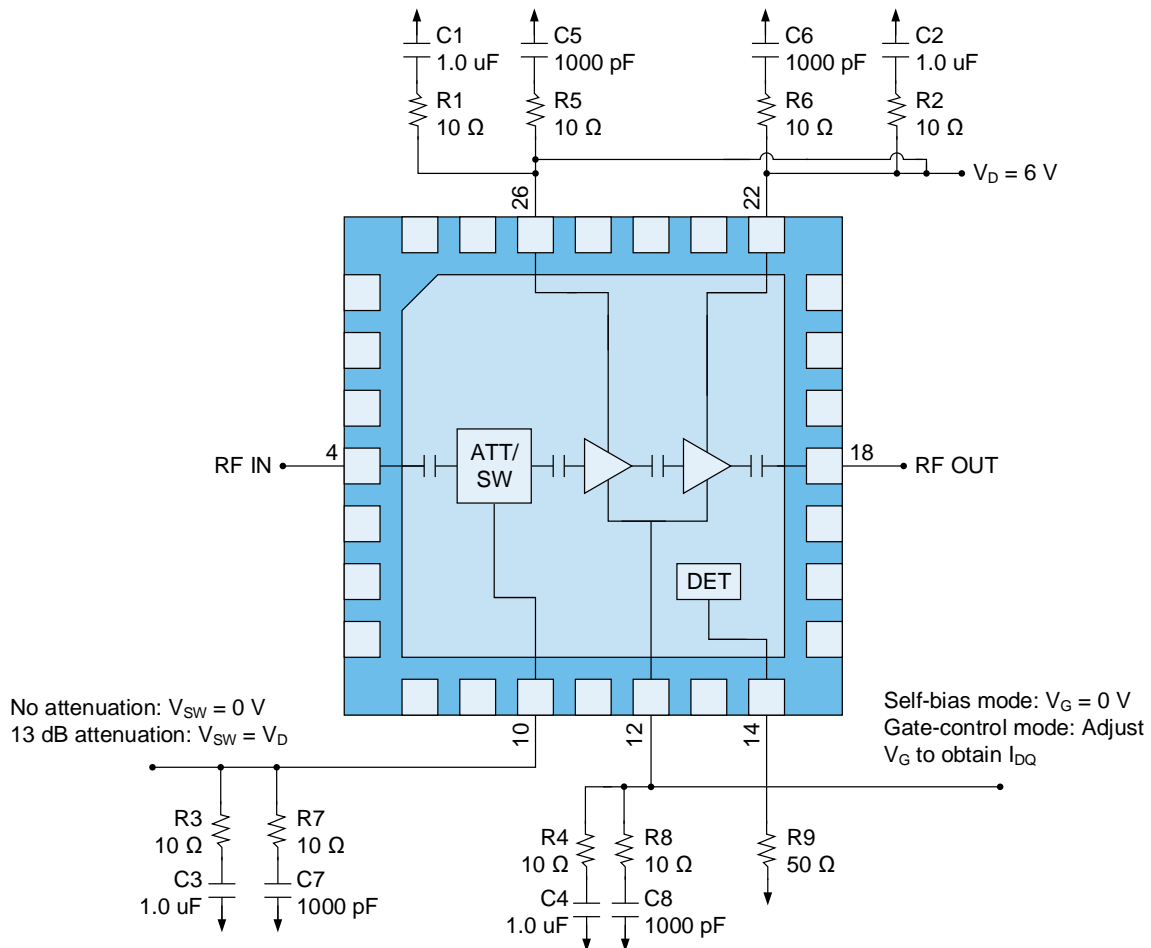
Dissipated Power and Median Lifetime

Test conditions, unless otherwise noted: T = 25 °C, V_{SW} = 0 V, part mounted to EVB



Test Conditions: 10 V; Failure Criterion = 10% reduction in I_{D_MAX}

Application Circuit



Bias-up Procedure

Set ID limit to 1000 mA, I_G limit to 12 mA

Self-biased mode: Set V_G to 0 V

Gate-control mode: Adjust V_G to obtain desired I_{DQ}

Increase V_D to +6 V

Apply RF signal

Bias-down Procedure

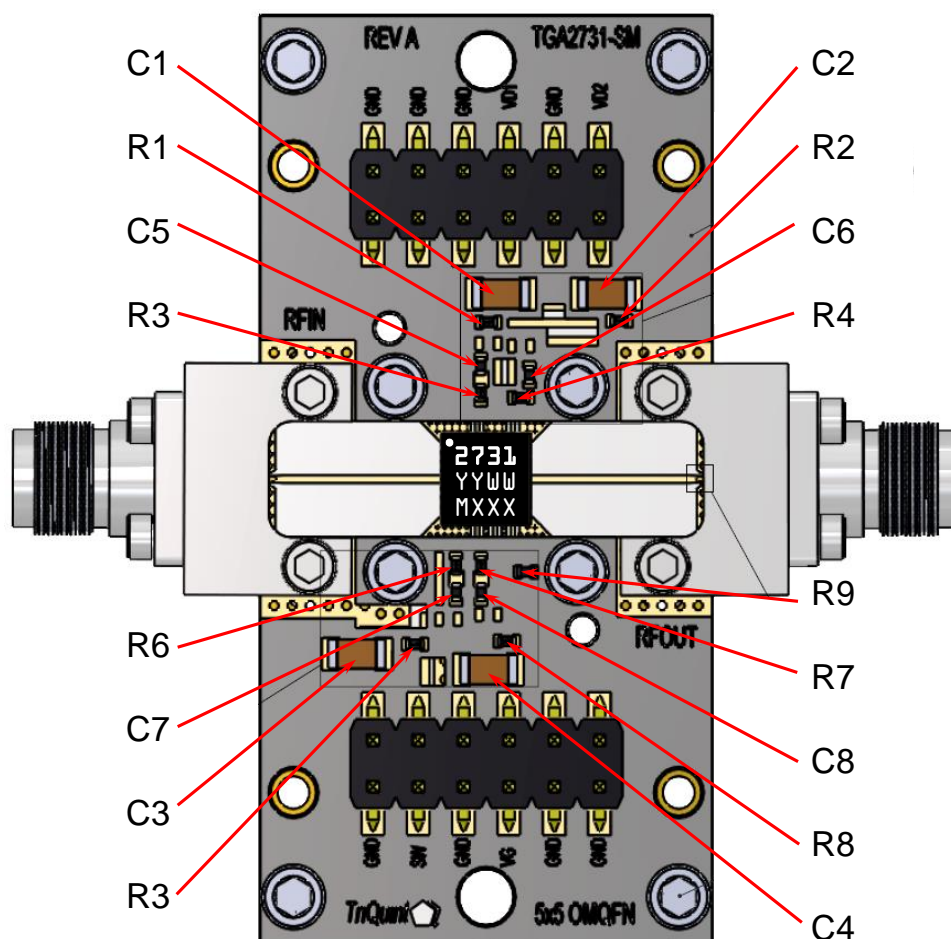
Turn off RF signal

Set V_D to 0 V. Ensure $I_{DQ} \sim 0\text{ mA}$

Turn off V_D supply

Turn off V_G , V_{SW} supply

Evaluation Board Layout



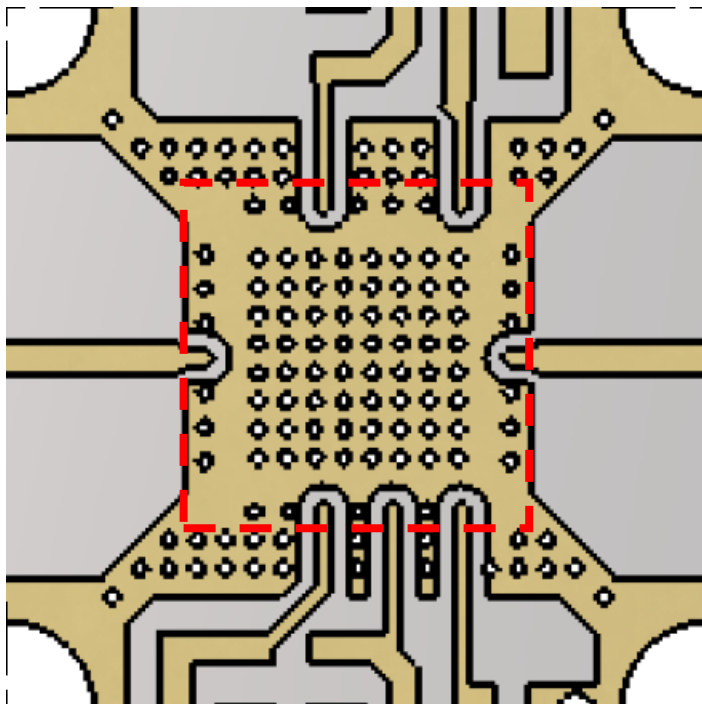
RF Layer is 0.008" thick Rogers Corp. RO4003C, $\epsilon_r = 3.38$. Metal layers are 0.5 oz. copper. The microstrip line at the connector interface is optimized for the Southwest Microwave end launch connector 1092-01A-5.

The pad pattern shown has been developed and tested for optimized assembly at Qorvo Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

Bill of Materials

| Reference Des. | Value | Description | Manuf. | Part Number |
|----------------|---------|--------------------------------|---------|-------------|
| C1–C4 | 1.0 uF | Cap., 50 V, 10% X5R, 1206 case | Various | |
| C5–C8 | 1000 pF | Cap., 50 V, 10% X7R, 0402 case | Various | |
| R1–R8 | 10 Ohms | Resistor, 0402 case | Various | |
| R9 | 50 Ohms | Resistor, 0402 case | Various | |

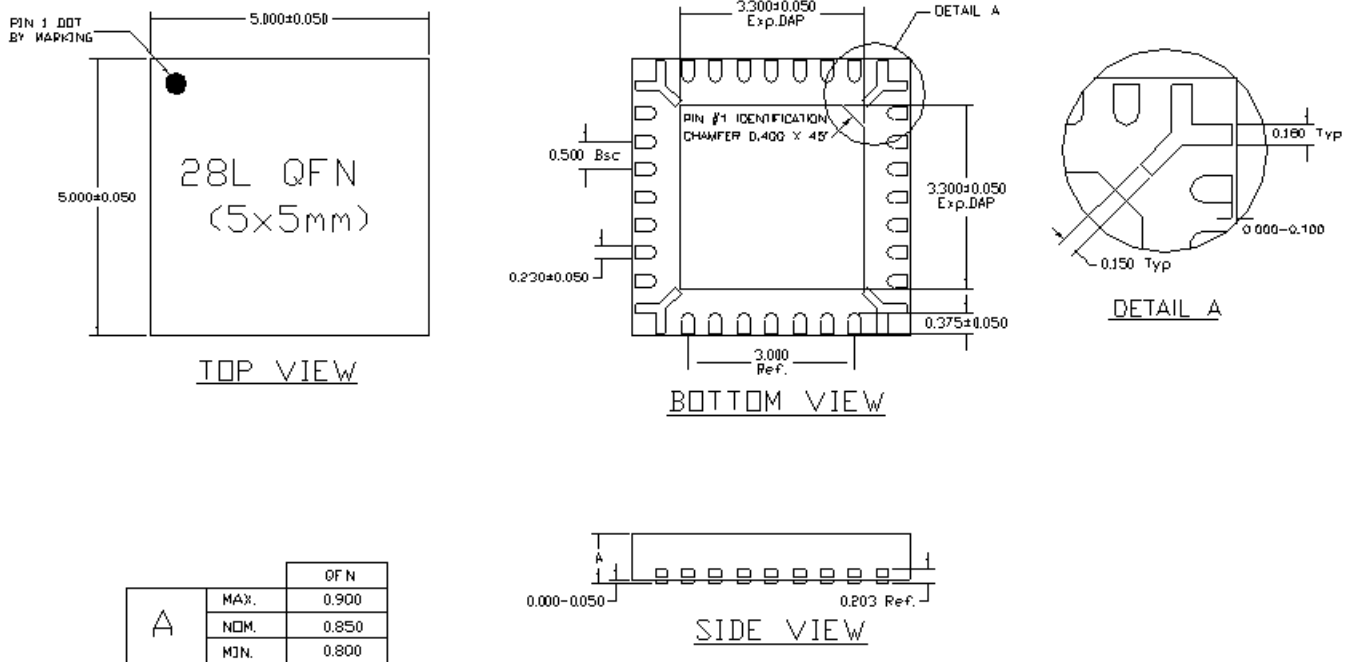
Mounting Detail



Notes:

1. Multiple copper filled vias are preferred for optimum thermal performance and to minimize inductance to ground.

Mechanical Information

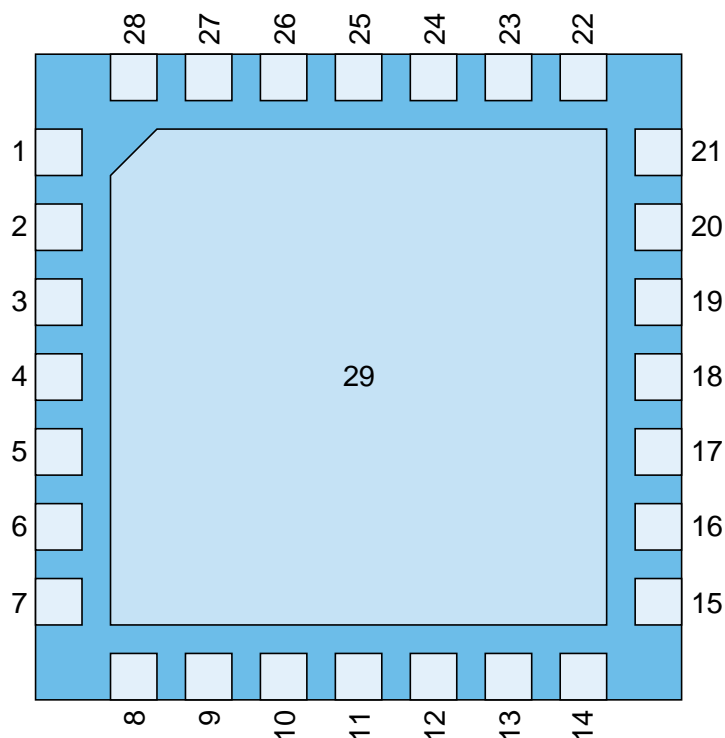


The TGA2731-SM will be marked with the "ZZZZ" and "YYWW" designators and a lot code marked below the part designator. Here, the "ZZZZ" will be "2731". The "YY" represents the last two digits of the year the part was manufactured, the "WW" is the work week, and the "XXXX" is an auto-generated number.

This package is lead-free/RoHS-compliant. This package is compatible with both lead free and tin-lead soldering processes.

Dimensions are in millimeters.

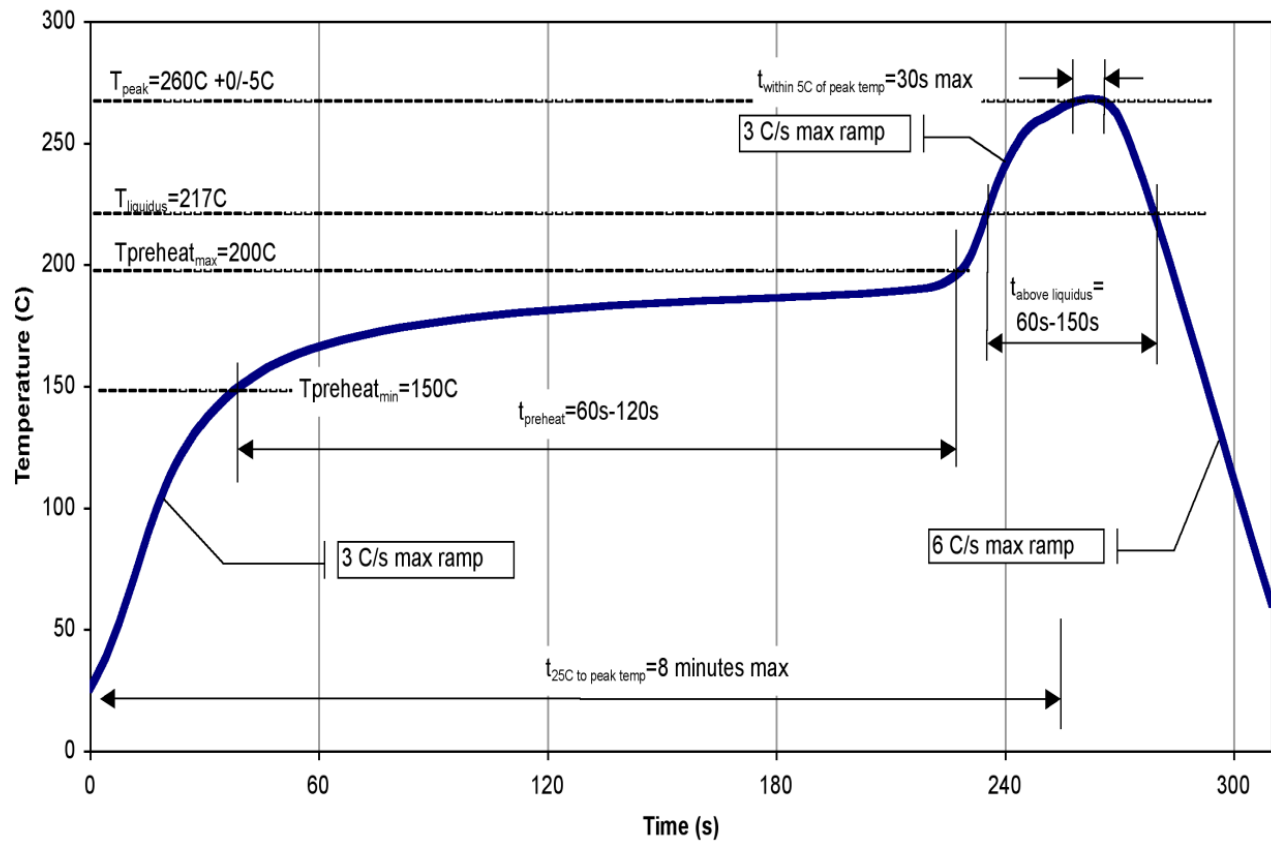
Pad Description



Bottom view of package base .

| Pin Number | Label | Description |
|---|-----------------|---|
| 1-3, 5-9, 11 13, 15-17, 19-21, 23-25, 27-28 | No Connect | No internal connection. Pads on PCB should be grounded to improve RF isolation |
| 4 | RF Input | RF input, matched to 50 Ω , DC blocked |
| 10 | V _{sw} | Input attenuator switch control voltage for gain control |
| 12 | V _G | Gate voltage |
| 14 | Power Sample | Coupled output power |
| 18 | RF Output | RF output, matched to 50 Ω , DC blocked |
| 22 | V _{D2} | Second stage drain voltage. Bias network required |
| 26 | V _{D1} | First stage drain voltage. Bias network required |
| 29 | GND | Ground paddle; must be grounded using plated through/copper filled via holes on PCB to improve isolation and for heat sinking |

Recommended Soldering Temperature Profile



Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|--------|---------------------------|
| ESD – Human Body Model (HBM) | 1A | JEDEC/JESD22-A114 |
| MSL – Moisture Sensitivity Level | MSL3 | JEDEC/IPC/JEDEC J-STD-020 |



Caution!
ESD-Sensitive Device

Solderability

Compatible with the latest version of J-STD-020 Lead free solder, 260 °C.

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Qorvo:

Web: www.qorvo.com

Tel: 1-844-890-8163

Email: customer.support@qorvo.com

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